



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



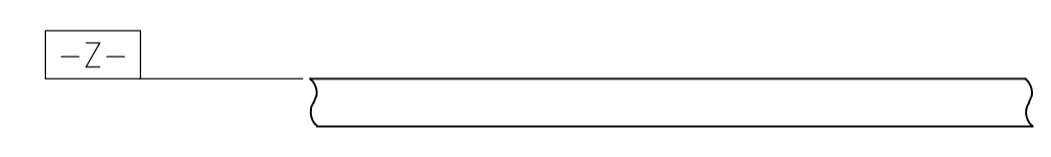
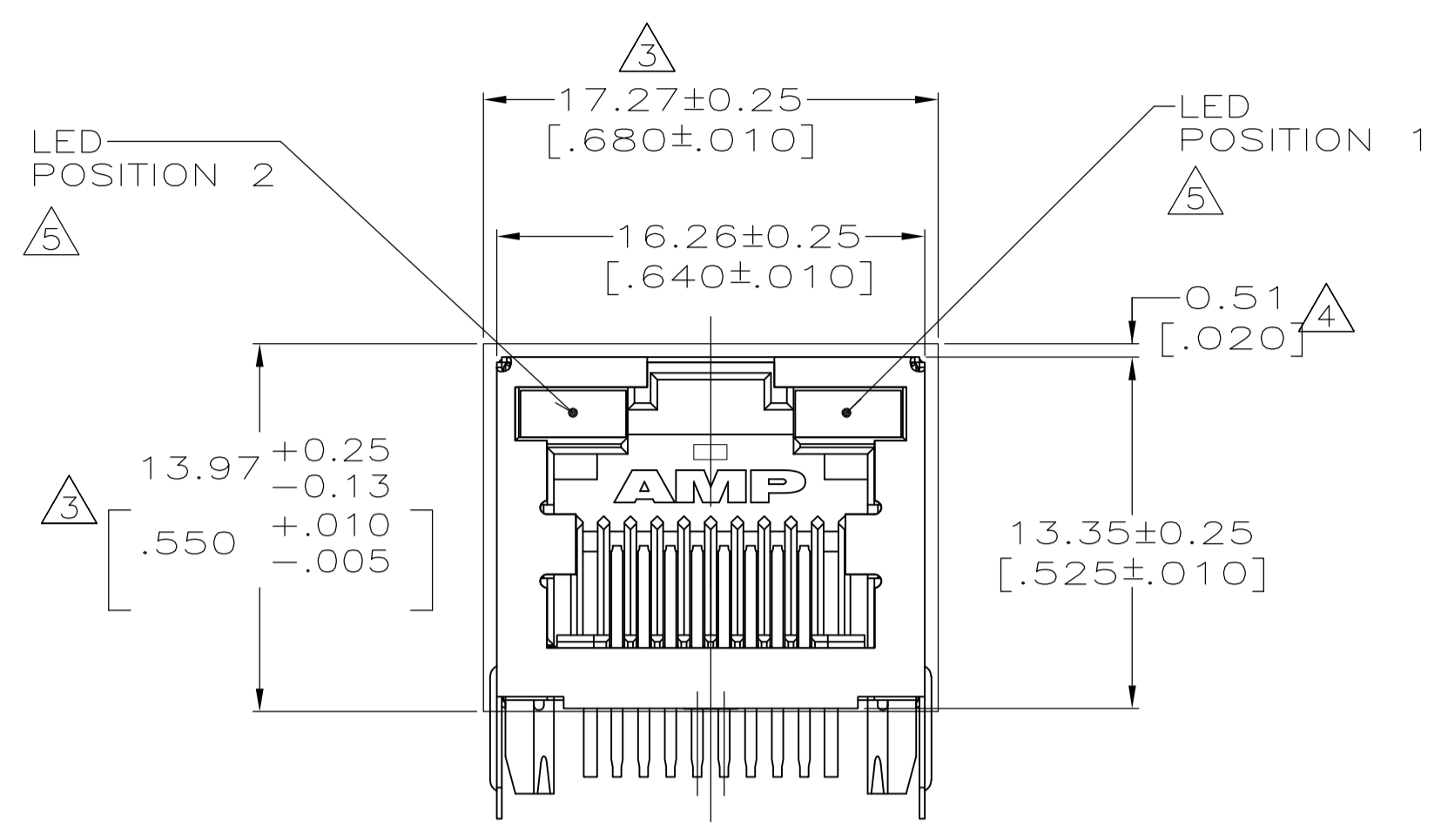
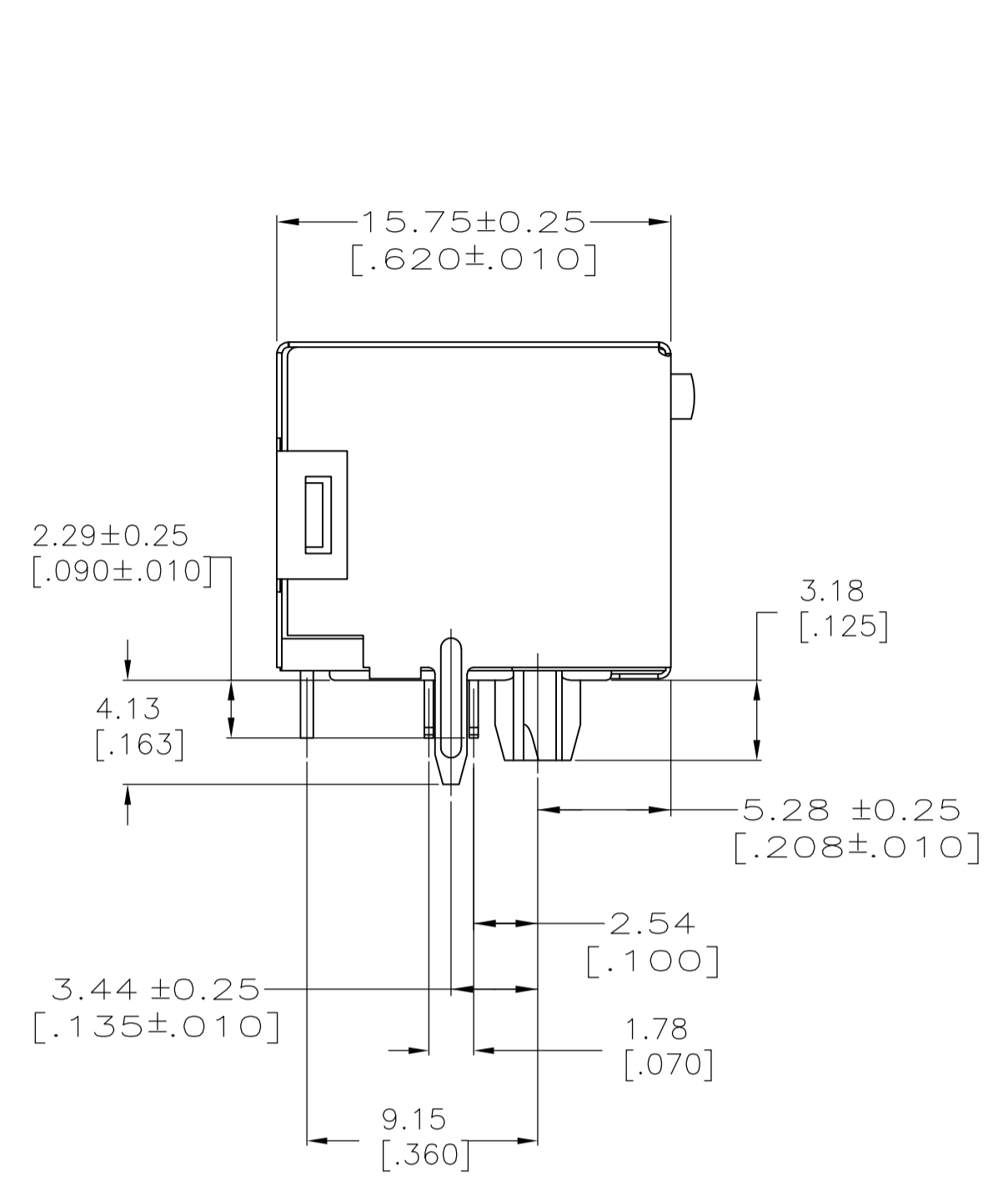
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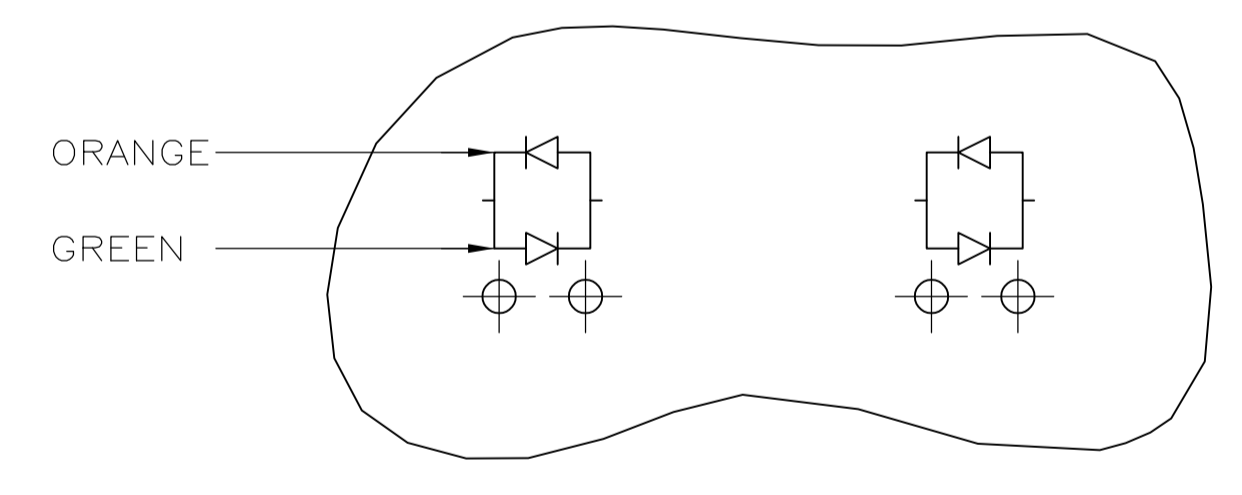
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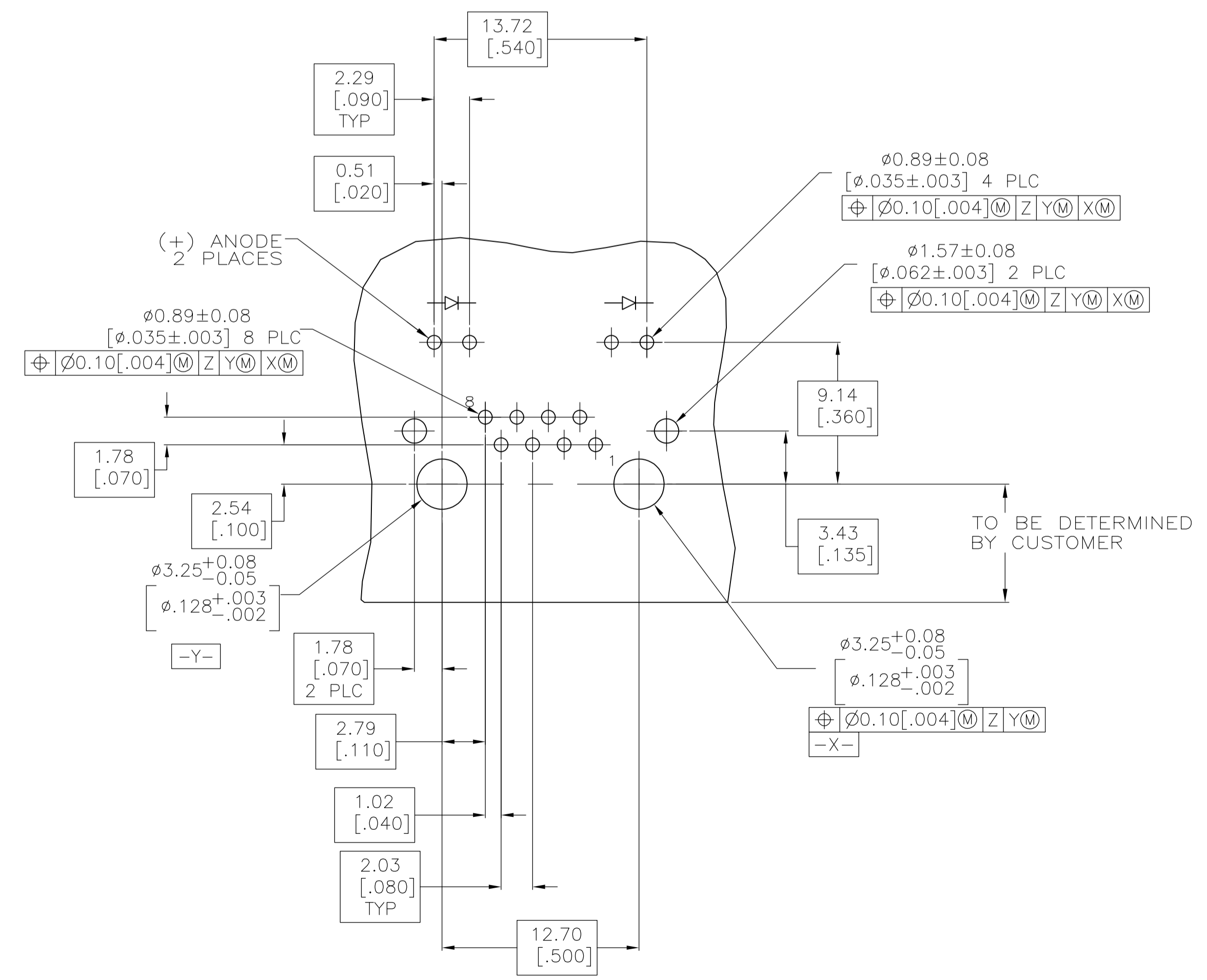




- MATERIAL:
HOUSING - HIGH TEMPERATURE THERMOPLASTIC, COLOR: BLACK, UL94V-0
TERMINALS - 0.36[.014] THICK PHOS BRONZE PLATED WITH 3.81µm[.000150] MIN THICK BRIGHT TIN LEAD IN SOLDER AREA, 1.27µm[.000050] MIN GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27µm[.000050] MIN THICK NICKEL.
SHIELD - 0.196[.0077] THICK COPPER ZINC ALLOY PREPLATED WITH 1.27µm[.000050] MIN SATIN NICKEL WITH 2.03µm[.000080] MIN TIN POST DIPPED ON PCB GROUND TABS
LIGHT EMITTING DIODE (LED) - DIFFUSED EPOXY LENS, 0.51 X 0.51[.020 X .020] CARBON STEEL WIREFRAME LEADS PLATED WITH 8.89µm[.000350] TIN/COPPER OVER 2.03µm[.000080] SILVER OVER 1.02µm[.000040] NICKEL UNDERPLATE OVER 2.03µm[.000080] COPPER UNDERPLATE
 - JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- △ RECOMMENDED PANEL OPENING DIMENSIONS.
 - △ RECOMMENDED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.
 - △ SEE TABLE FOR COLOR OF LEDS AND NUMBER REQUIRED.
 - 6. THIS MODULAR JACK WITH INTEGRATED LED IS NOT IR REFLOW SOLDERING PROCESS COMPATIBLE.
 - △ OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI



LED CURRENT DIAGRAM
1116075-7 ONLY



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT
(COMPONENT SIDE)

OBsolete	YELLOW/GREEN	YELLOW/GREEN	1116075-8
	ORANGE/GREEN	ORANGE/GREEN	1116075-7
	YELLOW	YELLOW	1116075-6
	GREEN	GREEN	1116075-5
	GREEN	YELLOW	1116075-4
△ OBsolete	YELLOW	-	1116075-3
	-	GREEN	1116075-2
	YELLOW	GREEN	1116075-1
	POSITION 2	POSITION 1	
	INDICATOR COLOR		PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: mm	TOLERANCES UNLESS OTHERWISE SPECIFIED:	DIN T. SPRINKLE 08DEC97	CHK T. SPRINKLE 08DEC97	APVD M. DERSTINE 08DEC97	NAME
	0 PLC ± -				INVERTED MODULAR JACK ASSEMBLY, 1X1, SHIELDED, LED
	1 PLC ± -				114-2154
	2 PLC ± 0.25[.01]				APPLICATION SPEC
	3 PLC ± 0.13[.005]				108-1163-4
	4 PLC ± -				SIZE CAGE CODE DRAWING NO
	ANGLES ± -				A1 00779 1116075
MATERIAL SEE NOTE 1	FINISH SEE NOTE 1	WEIGHT			RESTRICTED TO
					CUSTOMER DRAWING SCALE 4:1 SHEET 1 OF 1 REV F2